



# SOT1230

plastic very thin small outline package; no leads; 6 terminals;  
body 1.1 x 0.9 x 0.47 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	XSON6
<b>Package type industry code</b>	XSON6
<b>Package style descriptive code</b>	XSON (extremely thin small outline; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	8-1-2013

Table 1. Package summary

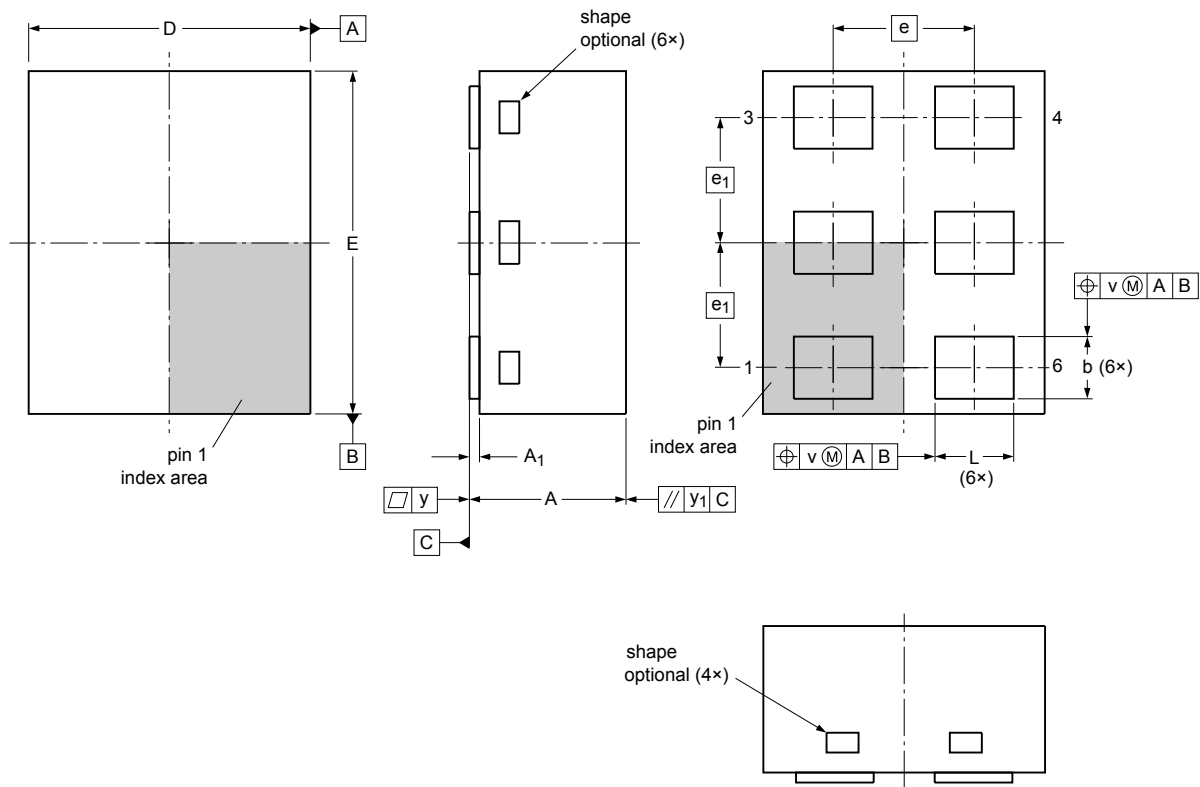
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.85	-	0.9	0.95	mm
E	package width	1.05	-	1.1	1.15	mm
A	seated height	0.44	-	0.47	0.5	mm
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	6	-	



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## 2. Package outline

XSON6: plastic very thin small outline package; no leads; 6 terminals; body 1.1 x 0.9 x 0.47 mm SOT1230



Dimensions (mm are the original dimensions)

Unit	A	A <sub>1</sub>	D	E	e <sub>1</sub>	e	b	L	V	Y	Y <sub>1</sub>
min	0.44		0.85	1.05			0.17	0.22			
mm nom	0.47		0.90	1.10	0.4	0.45	0.20	0.25	0.1	0.05	0.1
max	0.50	0.04	0.95	1.15			0.25	0.30			

Note

1. Dimension A is including plating thickness.

sot1230\_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1230					-13-01-02- 13-01-08

Fig. 1. Package outline XSON6 (SOT1230)

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### 3. Legal information

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## 4. Contents

---

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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